







Layer	Cust Thickness	Calc Thickness	Measured	Primary Stack	Description
Layer - 1		0.0005 0.0020			Taiyo 4000-BN 1/2oz Mix (Std Plt)
Layer - 2		0.0039 0.0006		1078 - 72%	R-5670K 1/2oz P/G
Layer - 3		0.0040 0.0006		0.0040 (1-3313)	R-5775K 1/2oz Sig
Layer - 4		0.0074 0.0006		1078 - 72%	R-5670K 1/2oz P/G
Layer - 5		0.0040 0.0006		0.0040 (1-2116)	R-1755V 1/2oz P/G
Layer - 6		0.0131 0.0006		1080 - 64% 7628 - 44%	R-1650V 1/2oz P/G
Layer - 7		0.0040 0.0006		0.0040 (1-2116)	R-1755V 1/2oz P/G
Layer - 8		0.0074 0.0006		1078 - 72%	R-5670K 1/2oz Sig
Layer - 9		0.0040 0.0006		0.0040 (1-3313)	R-5775K 1/2oz P/G
Layer - 10		0.0039 0.0020 0.0005		1078 - 72%	R-5670K 1/2oz Mix (Std Plt) Taiyo 4000-BN

Requirement	Req. Thickness	Tol +	Tol -	Calc Thick	Measured
Incl. Plating & Mask	0.0620	0.0062	0.0062	0.0615	
After Lamination	0.0582	0.0029	0.0029	0.0577	

Impedance Type	Layer	Actual	Plotted	Pitch	Plane	Target	Tol (ohms)	Predict
1  Surface MS	L1	0.0070	0.00775	-	-	50	5	50.88
	-	-	-	-	L2			
2  EC Microstrip	L1	0.0045	0.00525	0.0100	-	100	10	101.06
	-	0.0045	0.00525	-	L2			
3  EC Stripline	L3	0.00425	0.00475	0.0100	L2	100	10	101.66
	-	0.00425	0.00475	-	L4			
4  EC Stripline	L8	0.00425	0.00475	0.0100	L7	100	10	101.66
	-	0.00425	0.00475	-	L9			
5  Surface MS	L10	0.0070	0.00775	-	L9	50	5	50.88
	-	-	-	-	-			

Impedance Type	Layer	Actual	Plotted	Pitch	Plane	Target	Tol (ohms)	Predict
6  EC Microstrip	L10	0.0045	0.00525	0.0100	L9	100	10	101.06
	-	0.0045	0.00525	-	-			